

Features

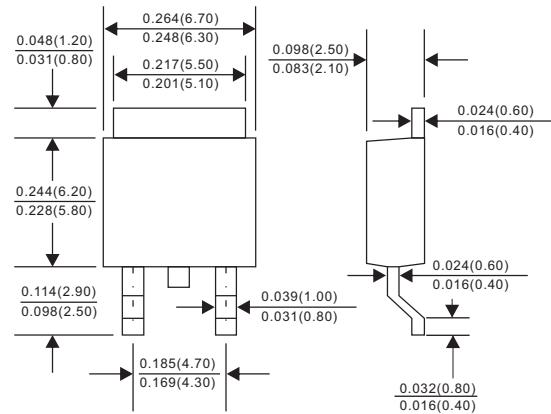
- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance.
- Low profile surface mounted application in order to optimize board space.
- Low power loss, high efficiency.
- High current capability, low forward voltage drop.
- High surge capability.
- Guardring for overvoltage protection.
- Ultra high-speed switching.
- Silicon epitaxial planar chip, metal silicon junction.
- **Moisture Sensitivity Level 1**

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, TO-252 / DPAK
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Mounting Position : Any
- Weight : Approximated 0.34 gram

Package outline

DPAK



Dimensions in inches and (millimeters)

Maximum ratings and Electrical Characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	I_o			8.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC methode)	I_{FSM}			150	A
Reverse current	$V_R = V_{RRM} \quad T_J = 25^{\circ}\text{C}$	I_R			0.5	mA
	$V_R = V_{RRM} \quad T_J = 100^{\circ}\text{C}$				20	
Storage temperature		T_{STG}	-55		+150	$^{\circ}\text{C}$

SYMBOLS	V_{RRM}^{*1} (V)	V_{RMS}^{*2} (V)	V_R^{*3} (V)	V_F^{*4} (V)	Operating temperature T_J , ($^{\circ}\text{C}$)
SKFM840Y-D	40	28	40	0.55	-55 to +125
SKFM860Y-D	60	42	60	0.70	-55 to +150
SKFM8100Y-D	100	70	100	0.85	

*1 Repetitive peak reverse voltage

*2 RMS voltage

*3 Continuous reverse voltage

*4 Maximum forward voltage@ $I_F = 8.0\text{A}$

Rating and characteristic curves

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

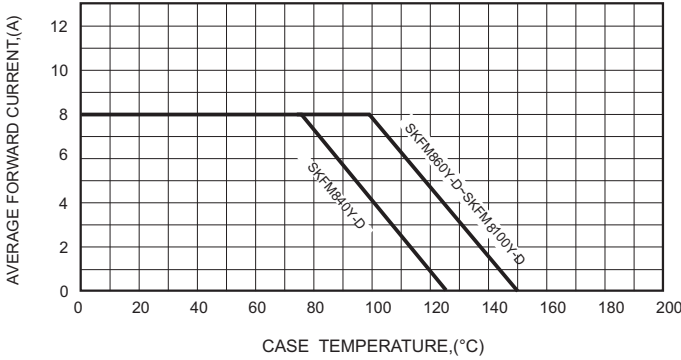


FIG.2-TYPICAL FORWARD CHARACTERISTICS

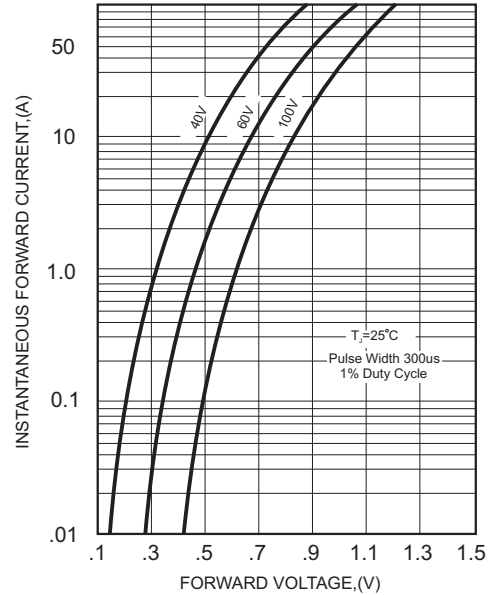


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

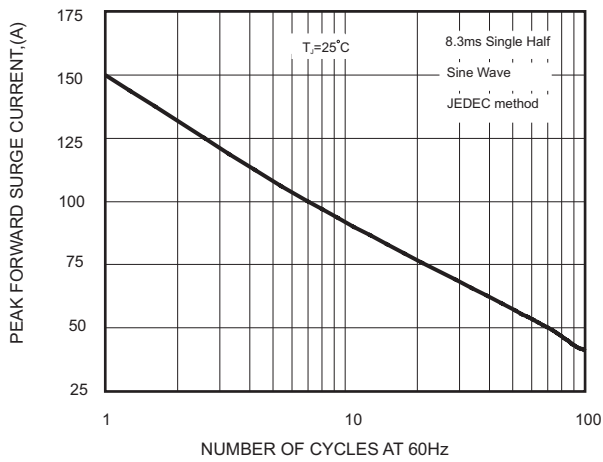
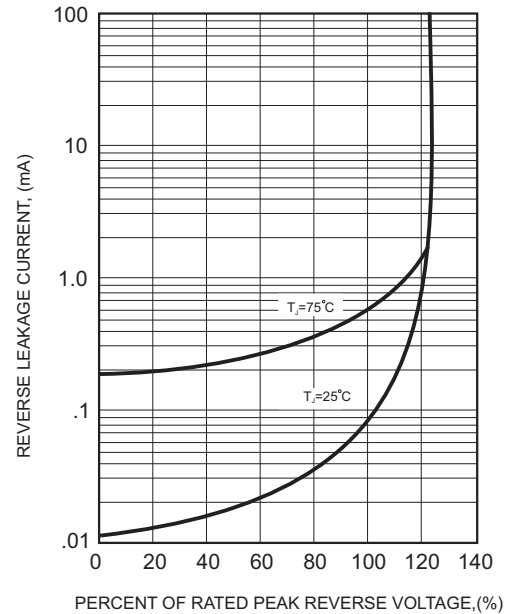
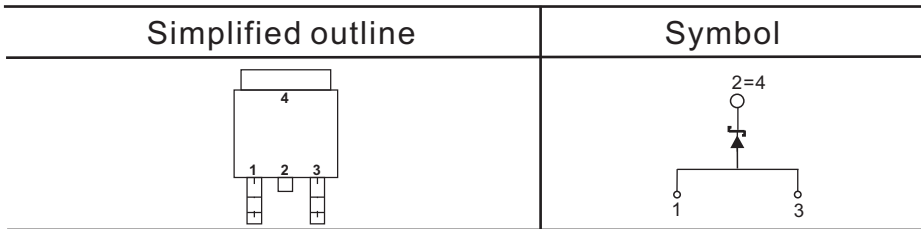


FIG.4 - TYPICAL REVERSE CHARACTERISTICS



Pinning information



Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
DPAK/TO-252	13"	3,000	8.0	6,000	335*335*43	330	350*330*360	48,000	22.0

Marking

Type number	Marking code
SKFM840Y-D-TH	SK840Y
SKFM860Y-D-TH	SK860Y
SKFM8100Y-D-TH	SK8100Y

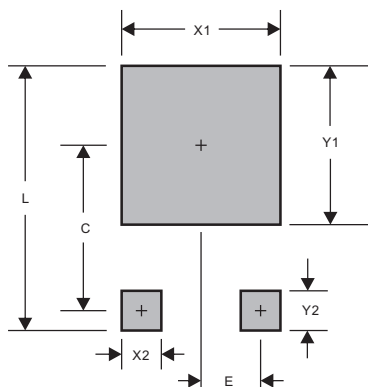
Note: D: Package code, DPAK
-T: Taping Reel

Pb-Free package is available

RoHS product for packing code suffix "G"

Halogen free product for packing code suffix "H"

Suggested solder pad layout



PACKAGE	DPAK
C	0.272(6.90)
E	0.091(2.30)
L	0.457(11.60)
X1	0.276(7.00)
X2	0.059(1.50)
Y1	0.276(7.00)
Y2	0.098(2.50)

Dimensions in inches and (millimeters)